# PRODUCT SPECIFICATION

CS4002B-D-BSXTSWN-100

*V1.0* 

February 20, 2009

**E** Easterntronic LCD Group

# **REVISION RECORD**

REV	Description	Date
V1.0	First Release	Feb 20, 2009

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1. Type Number And Description

Type Number : CS4002B-D-BSXTSWN-100

Description 40 Characters X 2 Lines

LCD Panel Blue- STN, Negative, Transmissive

Viewing angle 6H

Duty 1/16

1/5 Bias

Operating Temperature:  $-20^{\circ}C - 70^{\circ}C$ 

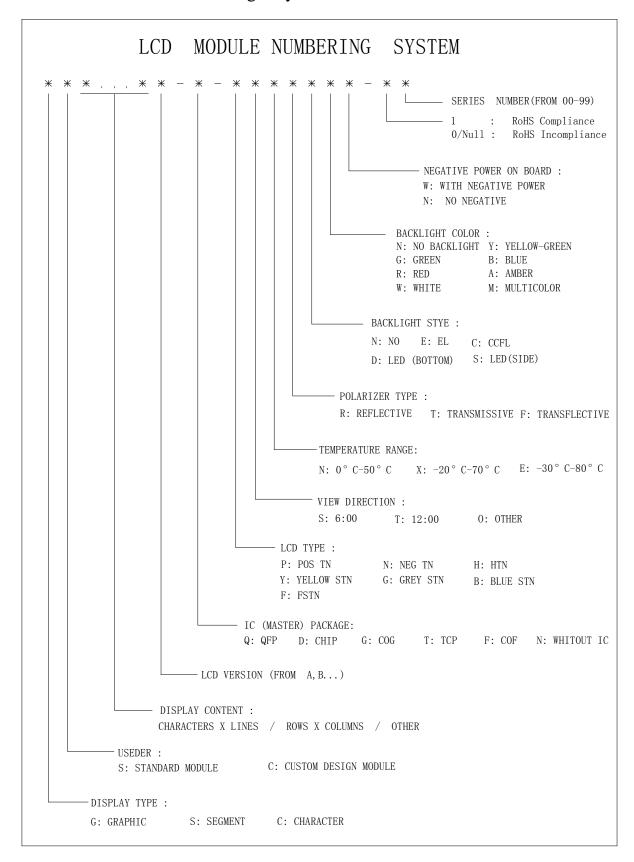
 $-30^{\circ}C - 80^{\circ}C$ Storage Temperature :

ST7066U-OA Or Equivalent Controller

IC package Bonding

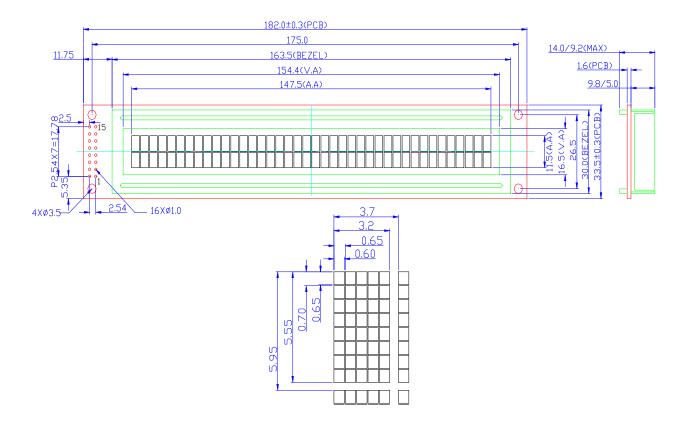
BackLight White LED, Side

## 2. LCD Module Numbering System



### 3. MECHANICAL SPECIFICATIONS

ITEM	STANDARD VALUE	UNIT
NUMBER OF CHARACTERS	40 CHARACTERS X 2 LINES	
CHARACTER FORMAT	5 X 8 DOTS	
MODULE DIMENSION	182.0(W) X 33.5(H) X 14.0(T)	mm
EFFECTIVE DISPLAY AREA	154.4(W) X 16.5(H)	mm
CHARACTER SIZE	3.20 (W) X 5.55(H)	mm
CHARACTER PITCH	3.7 (W) X 5.95(H)	mm
DOT SIZE	0.60(W) X 0.65(H)	mm
DOT PITCH	0.65(W) X 0.70(H)	mm
APPROX WEIGHT	TBD	



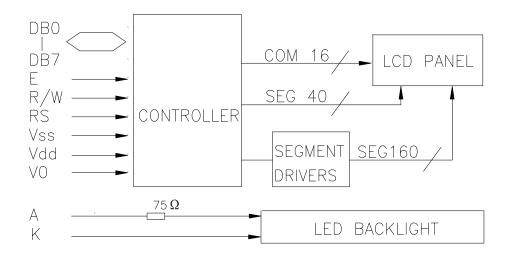
<sup>\*</sup> Remark : General tolerance refers this model. (±0.2mm)

# 4. Electrical Block Diagram

#### Pin Definition 4.1

PIN	SYMBOL	FUNCTION
1	Vss	Power Supply(GND)
2	Vdd	Power Supply(+5V)
3	Vo	Contrast Adjust
4	RS	Instruction/Data Register Select
5	R/W	Data Read/Write
6	Е	Enable Signal
7-14	DB0-DB7	Data Bus Line
15	A	Power Supply For Backlight (+5V)
16	K	Power Supply For Backlight (0V)

#### 4.2 Electrical Block Diagram



#### 4.3 Display Character Address Code

DISPLAY	POSITION	1 :	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21 :	22 %	23 2	24 2	5 20	6 27	28	28	30	31	32	33	34	35	36	37 .	38	39 40
IC1	LINE1	00 (	)1	02	03	04	05	06	07	08	09	0A	OB	00	OD)	0E	0F	10	11	12	13	14	15	16	17	18 1	9 1/	4 1E	10	10	1E	1F	20	21	22	23	24	25	26 27
DDRAM	LINE2	40 4	41	42	43	44	45	46	47	48	49	4A	4B	4C	4D	4E	4F	50	51	52	53	54	55	56	57 5	58 5	9 5	4 5E	5C	5D	5E	5F	60	61	62	63	64	65	66 67

## 5. Absolute Maximum Ratings

#### Electrical Maximum Ratings(Ta=25deg C) 5.1

ITEM	SYMBOL	CONDITION	MIN	MAX	UNIT
Supply Voltage (Logic)	Vdd – Vss	-	0	7.0	V
Supply Voltage (LCD Drive)	Vdd – V0	-	0	11.5	V
Input Voltage	Vi	-	-0.3	Vdd +0.3	V

#### 5.2 **Environmental Conditions**

ITEM	SYMBOL	CONDITION	MIN	MAX	UNIT
Operating Temp	Topr	Dry	-20	70	deg C
Storage Temp	Ttsg	Dry	-30	80	deg C

#### 6. ELECTRICAL SPECIFICATIONS

#### Electrical Characteristics at Ta=25 deg C, Vdd = 5V + / - 5%6.1

ITEM	SYMB OL	CONDITION	MIN	TYP	MAX	UNIT
Supply Voltage (logic)	Vdd-Vss	-	4.5	5	5.5	V
Supply Voltage (LCD)	Vdd-V0	Vdd = 5V	4.6	4.8	5.0	V
Input signal voltage	V-ih	"H" level	0.7Vdd	-	Vdd	V
(for E, DB0-7,R/W,RS)	V-iI	"L" level	0	-	0.6	V
Supply Current (logic)	Icc	-	0.9	1	1.2	mA
Supply Current (LCD)	lo	-	0.15	0.22	0.27	mA
*Supply Voltage (B/L )	VA-K	-	4.7	5.0	5.4	V
*Supply Current (B/L )	If	-	-	26	50	mA
*Peak forward current(B/L)	Ifp	I mseo pulse 10% Duty Cycle	-	-	120	mA
*Power dissipation(B/L)	Pd		-	-	170	mW

<sup>\*</sup>For operation above 25°C, the If \ Ifp&Pd must be derated, the current derating is -0.72 mA/ Blacklight working current must not more than 60% of the Ifmax or Ifpmax according to the working temperature.

#### 6.2 Timing Specifications at Ta = 25 deg C, Vdd = 5V + /-10%, Vss = 0V

## 6.2.1 Write mode

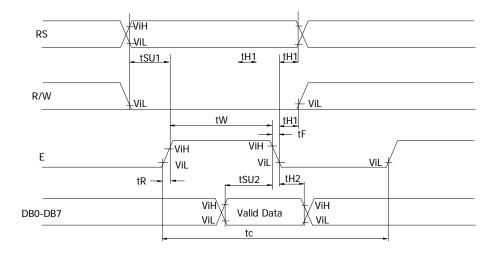
ITEM	SYMBOL	MIN	MAX	UNIT
E cycle time	tc	1200	-	ns
E rise time	tR	-	25	ns
E fall time	tF	-	25	ns
E-pulse width (H, L)	tw	140	-	ns
R/W and RS set-up time	tsul	0	-	ns
R/W and RS hold time	tH1	10	-	ns
Data set-up time	tsu2	40	-	ns
Data hold time	tH2	10	-	ns

### 6.2.2 Read mode

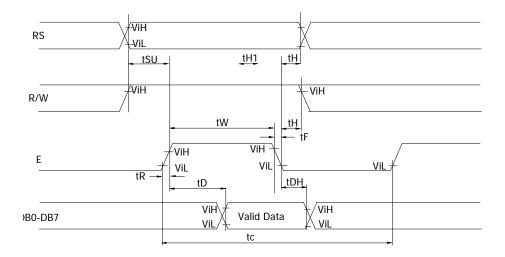
ITEM	SYBOL	MIN	MAX	UNIT
E cycle time	tc	1200	-	ns
E rise time	tR	-	25	ns
E fall time	tF	-	25	ns
E-pulse width (H, L)	tw	140	-	ns
R/W and RS set-up time	tsu	0	-	ns
R/W and RS hold time	tH	10	-	ns
Data output delay	tD	-	120	ns
Data hold time	tDH	20	-	ns

# 6.2.3 Timing Diagram

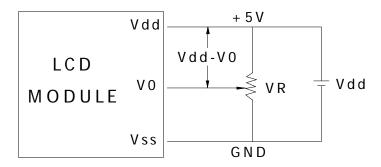
### WRITE MODE TIMING DIAGRAM



#### READ MODE TIMING DIAGRAM



# 7. Power Supply For LCD Module



Vdd-V0: LCD Driving Voltage

VR: 10K - 20K

# 8. Electro-Optical Characteristic

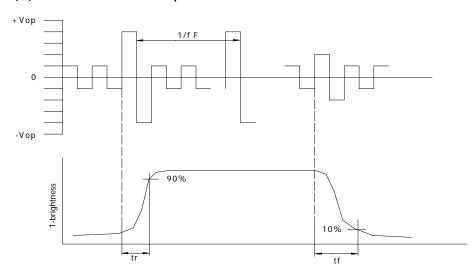
ITEM	SYMBOL	CONDITION	MIN.	TYP.	MAX.	UNIT	REF.
Contrast	CR	25℃		10			Note1
Rise Time	tr	25℃		160	240	ms	Note2
Fall Time	tf	25℃		100	150	ms	note 2
Viouving Angle	θ 1- θ 2	25℃			60	DEG	Note 3
Viewing Angle	Ø1, Ø2	25 C	-40		40	DEG	Note 3
Frame Frequency	Ff	25℃		70		Hz	note 2

Note(1): Contrast ratio is defined under the following condition:

- CR= <u>brightness of selected condition</u> brightness of non- selected condition
- (a). Temperature-----25C

- (b). Frame Frequency-----64Hz
- (c). Viewing angle-----  $\theta = 0$ ,  $\emptyset = 0$
- (d). Operating Voltage---4.8V

## Note(2): definition of response time:

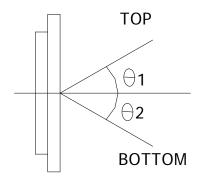


### Condition:

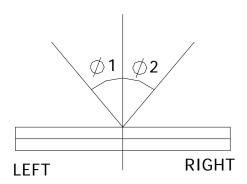
- (a). Temperature-----25C
- (b). Frame Frequency-----64Hz
- (c). Viewing angle-----  $\theta = 0$ ,  $\emptyset = 0$
- (d). Operating Voltage---4.8V

# Note(3): definition of view angle:

### **TOP-BOTTOM DIRECTION**



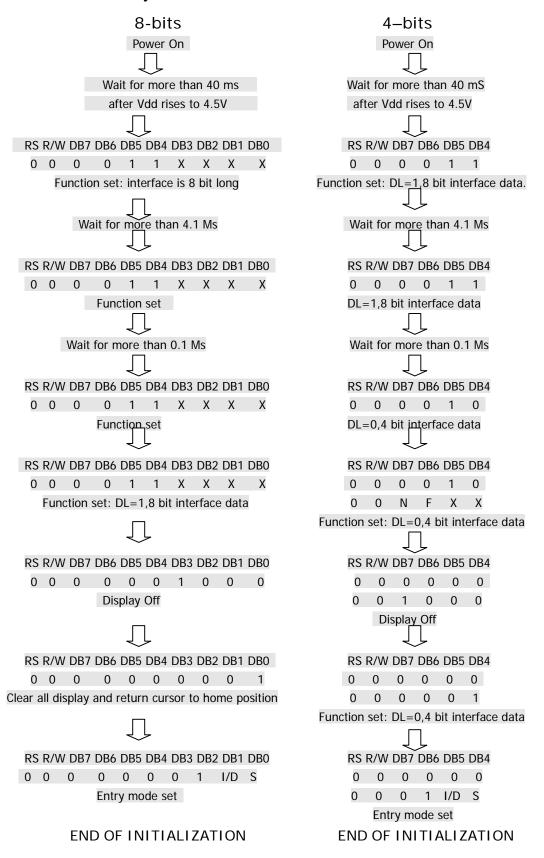
### RIGHT-LEFT DIRECTION



# 9. Instruction Table

Display Displ	Function	R	R	D	D	D	D	D	D	D	D	Description	Execu	u
Clear Display    Return    O    O    O    O    O    O    O		S	W	В	В	В	В	В	В	В	В		Time	*
Clear Display    Return    O    O    O    O    O    O    O				7	6	5	4	3	2	1	0		(Max	()
Display	Clear	0	0		_	_	_						1.64mS	
Entry 0 0 0 0 0 0 1 1 S Set cursor moving direction and enable the shift of the display. These operations are set D part of the display and performed during data write/read of DD RAM/CG RAM. 1/D=1: increment; 1/D=0: decrement; S=1: whole display shift when data is written.  Display 0 0 0 0 0 0 1 D C B Set display (D),cursor(C) and blinking of cursor(B) 40 μ S ON/OFF. D=1:display ON; D=0: display OFF. C=1:Cursor ON; C=0:cursot OFF. B=1:Blink ON; B=0, Blink OFF.  Cursor or 0 0 0 0 1 S R X X Move the cursor and shift the display without A0 μ S changing DDRAM contents. S/C=1: Display Shift; S/C=0:Cursor move. R/L=1:shift to right; R/L=0:shift to left.  Function 0 0 0 0 1 DNF X X Set interface data length (DL), number of display 40 μ S lines (N) and character font (F).DL=1: 8 bits; DL=0: 4 bits. N=1: 2 lines; N=0: 1 lines. F=1: 5X11 dots; F=0: 5X7 dots.  Set CG 0 0 0 1 ACG Set CG RAM address. CG RAM data is sent and 40 μ S received after this setting.  Read BF 0 1 B AC Read BUSY FLAG (BF) and the contents of the address counter. BF=1: internal operation; BF=0: can accept instruction.  Write Data 1 0 WRITE DATA Write data into DD RAM or CG RAM.  Verification and enable the 40 μ S received after this setting.  Read Data 1 0 READ DATA Read data from DD RAM or CG RAM.  Verification and enable the 40 μ S received after this setting.	Display													
Entry 0 0 0 0 0 0 1 1 S Set cursor moving direction and enable the shift of the display. These operations are set D part of the display and performed during data write/read of DD RAM/CG RAM. 1/D=1: increment; 1/D=0: decrement; S=1: whole display shift when data is written.  Display 0 0 0 0 0 0 1 D C B Set display (D),cursor(C) and blinking of cursor(B) 40 μ S ON/OFF. D=1:display ON; D=0: display OFF. C=1:Cursor ON; C=0:cursot OFF. B=1:Blink ON; B=0, Blink OFF.  Cursor or 0 0 0 0 1 S R X X Move the cursor and shift the display without A0 μ S changing DDRAM contents. S/C=1: Display Shift; S/C=0:Cursor move. R/L=1:shift to right; R/L=0:shift to left.  Function 0 0 0 0 1 DNF X X Set interface data length (DL), number of display 40 μ S lines (N) and character font (F).DL=1: 8 bits; DL=0: 4 bits. N=1: 2 lines; N=0: 1 lines. F=1: 5X11 dots; F=0: 5X7 dots.  Set CG 0 0 0 1 ACG Set CG RAM address. CG RAM data is sent and 40 μ S received after this setting.  Read BF 0 1 B AC Read BUSY FLAG (BF) and the contents of the address counter. BF=1: internal operation; BF=0: can accept instruction.  Write Data 1 0 WRITE DATA Write data into DD RAM or CG RAM.  Verification and enable the 40 μ S received after this setting.  Read Data 1 0 READ DATA Read data from DD RAM or CG RAM.  Verification and enable the 40 μ S received after this setting.	Return	0	0	0	0	0	0	0	0	1	Χ	Return the cursor to the home position. DD RAM	1.64mS	
Entry 0 0 0 0 0 0 0 0 1 1 S R X X Move the cursor and shift the display without A0 μ S Charles bet Cursor or 0 0 0 0 0 1 1 D N F X X Set interface data length (DL), number of display Shift to left.  Function 0 0 0 1 D N F X X Set interface data length (DL), number of display A0 μ S lines (N) and character font (F).DL=1: 8 bits; DL=0: 4 bits. N=1: 2 lines; N=0: 1 lines. F=1: 5X11 dots; F=0: 5X7 dots.  Set CG 0 0 0 1 ADD Set DD RAM address. DD RAM data is sent and 40 μ S received after this setting.  Read BF 0 1 B AC Read BUSY FLAG (BF) and the contents of the address counter. BF=0: can accept instruction.  Write Data 1 0 WRITE DATA Write data into DD RAM or CG RAM.  V Shift of the display. These operations are performed during display. Shift the display of DD RAM or CG RAM.  V Set CG RAM or CG RAM.  V RITE DATA Read data from DD RAM or CG RAM.  V READ DATA Read data from DD RAM or CG RAM.	Home													
mode set												to zero.		
mode set	Entry	0	0	0	0	0	0	0	1	1	S	Set cursor moving direction and enable the	40 μ S	
performed during data write/read of DD RAM/CG RAM. 1/D=1: increment; 1/D=0: decrement; S=1: whole display shift when data is written.  Display ON/OFF ON/OFF ON/OFF D=1: display ON; D=0: display OFF. C=1:Cursor ON; C=0:cursot OFF. B=1:Blink ON; B=0, Blink OFF.  Cursor Or O O O O O O O S RX X Move the cursor and shift the display without changing DDRAM contents. S/C=1: Display Shift; S/C=0:cursor move. R/L=1:shift to right; R/L=0:shift to left.  Function O O O O O I DNF X X Set interface data length (DL), number of display 40 μ S lines (N) and character font (F).DL=1: 8 bits; DL=0: 4 bits. N=1: 2 lines; N=0: 1 lines. F=1: 5X11 dots; F=0: 5X7 dots.  Set CG O O O I ACG Set CG RAM address. CG RAM data is sent and 40 μ S received after this setting.  Set DD O O I ADD Set DD RAM address. DD RAM data is sent and 40 μ S received after this setting.  Read BF O I B AC Read BUSY FLAG (BF) and the contents of the O μ S address counter. BF=1: internal operation; BF=0: can accept instruction.  Write Data I O WRITE DATA Write data into DD RAM or CG RAM. 40 μ S**	mode									/				
RAM. 1/D=1: increment; 1/D=0: decrement; S=1: whole display shift when data is written.  Display 0 0 0 0 0 0 1 D C B Set display (D),cursor(C) and blinking of cursor(B) 40 μ S ON/OFF. D=1:display ON; D=0: display OFF. C=1:Cursor ON; C=0:cursot OFF. B=1:Blink ON; B=0, Blink OFF. C=1:Cursor ON; C=0:cursot OFF. B=1:Blink ON; B=0, Blink OFF. C=1:Cursor ON; C=0:cursot OFF. B=1:Blink ON; B=0, Blink OFF. C=1:Cursor on; C=0:cursot OFF. B=1:Blink ON; B=0, Blink OFF. C=1:Cursor on; C=0:cursot OFF. B=1:Blink ON; B=0, Blink OFF. C=1:Cursor on; C=0:cursot OFF. B=1:Blink ON; B=0, Blink OFF. C=1:Cursor on; C=0:cursot OFF. B=1:Blink ON; B=0, Blink OFF. C=1:Cursor on; C=0:cursot OFF. B=1:Blink ON; B=0, Blink OFF. C=1:Cursor on; C=0:cursot OFF. B=1:Blink ON; B=0, Blink OFF. C=1:Cursor on; C=0:cursot OFF. B=1:Blink ON; B=0, Blink OFF. C=1:Cursor on; C=0:cursot OFF. B=1:Blink ON; B=0, Blink OFF. C=1:Cursor OFF. B=1:Blink ON; B=1:Blink ON; B=1:Blink ON; B=1:Blink ON; B=1:Blink ON; B=1:Blink ON	set									D		. ,		
Whole display shift when data is written.  Display 0 0 0 0 0 0 1 DC B Set display (D), cursor(C) and blinking of cursor(B) 40 μ S ON/OFF. D=1:display ON; D=0: display OFF. C=1:Cursor ON; C=0:cursot OFF. B=1:Blink ON; B=0, Blink OFF.  Cursor or 0 0 0 0 0 1 S R X X Move the cursor and shift the display without 40 μ S Display shift; Shift CL S/C=0:Cursor move. R/L=1:shift to right; R/L=0:shift to left.  Function 0 0 0 0 1 DNF X X Set interface data length (DL), number of display 40 μ S lines (N) and character font (F).DL=1: 8 bits; DL=0: 4 bits. N=1: 2 lines; N=0: 1 lines. F=1: 5X11 dots; F=0: 5X7 dots.  Set CG 0 0 0 1 ACG Set CG RAM address. CG RAM data is sent and 40 μ S received after this setting.  Set DD 0 0 1 ADD Set DD RAM address. DD RAM data is sent and 40 μ S received after this setting.  Read BF 0 1 B AC Read BUSY FLAG (BF) and the contents of the 0 μ S address counter. BF=1: internal operation; BF=0: can accept instruction.  Write Data 1 0 WRITE DATA Write data into DD RAM or CG RAM.  Write Data 1 0 READ DATA Read data from DD RAM or CG RAM.														
Display O 0 0 0 0 0 1 D C B Set display (D), cursor(C) and blinking of cursor(B) 40 μ S ON/OFF. D=1:display ON; D=0: display OFF. C=1:Cursor ON; C=0:cursot OFF. B=1:Blink ON; B=0, Blink OFF.  Cursor or 0 0 0 0 0 1 S R X X Move the cursor and shift the display without changing DDRAM contents. S/C=1: Display Shift; S/C=0:Cursor move. R/L=1:shift to right; R/L=0:shift to left.  Function 0 0 0 0 1 DNF X X Set interface data length (DL), number of display lines (N) and character font (F).DL=1: 8 bits; DL=0: 4 bits. N=1: 2 lines; N=0: 1 lines. F=1: 5X11 dots; F=0: 5X7 dots.  Set CG 0 0 0 1 ACG Set CG RAM address. CG RAM data is sent and received after this setting.  Set DD 0 0 1 ADD Set DD RAM address. DD RAM data is sent and received after this setting.  Read BF 0 1 B AC Read BUSY FLAG (BF) and the contents of the address counter. BF=1: internal operation; BF=0: can accept instruction.  Write Data 1 0 WRITE DATA Write data into DD RAM or CG RAM.  S**  Read Data 1 0 READ DATA Read data from DD RAM or CG RAM.														
ON/OFF Control  ON/OFF. D=1:display ON; D=0: display OFF. C=1:Cursor ON; C=0:cursot OFF. B=1:Blink ON; B=0, Blink OFF.  Cursor or 0 0 0 0 0 0 1 S R X X Move the cursor and shift the display without 40 µ S changing DDRAM contents. S/C=1: Display Shift; S/C=0:Cursor move. R/L=1:shift to right; R/L=0:shift to left.  Function  O 0 0 0 0 1 D N F X X Set interface data length (DL), number of display 40 µ S lines (N) and character font (F).DL=1: 8 bits; DL=0: 4 bits. N=1: 2 lines; N=0: 1 lines. F=1: 5X11 dots; F=0: 5X7 dots.  Set CG 0 0 0 1 ACG Set CG RAM address. CG RAM data is sent and 40 µ S received after this setting.  Set DD 0 0 1 ADD Set DD RAM address. DD RAM data is sent and received after this setting.  Read BF 0 1 B AC Read BUSY FLAG (BF) and the contents of the address counter. BF=1: internal operation; BF=0: can accept instruction.  Write Data 1 0 WRITE DATA Write data into DD RAM or CG RAM.  40 µ S**  Read Data 1 0 READ DATA Read data from DD RAM or CG RAM.	Display	0	0	0	0	0	0	1	D	С	В	-	40 μ S	
Cursor or 0 0 0 0 0 1 S R X X Move the cursor and shift the display without 40 μ S Display Shift; shift C L S/C=0:Cursor move. R/L=1:shift to right; R/L=0:shift to left.  Function 0 0 0 0 1 D N F X X Set interface data length (DL), number of display lines (N) and character font (F).DL=1: 8 bits; DL=0: 4 bits. N=1: 2 lines; N=0: 1 lines. F=1: 5X11 dots; F=0: 5X7 dots.  Set CG 0 0 0 1 ACG Set CG RAM address. CG RAM data is sent and received after this setting.  Set DD 0 0 1 ADD Set DD RAM address. DD RAM data is sent and received after this setting.  Read BF 0 1 B AC Read BUSY FLAG (BF) and the contents of the address counter. BF=1: internal operation; BF=0: can accept instruction.  Write Data 1 0 WRITE DATA Write data into DD RAM or CG RAM.  40 μ S**  Read Data 1 0 READ DATA Read data from DD RAM or CG RAM.	ON/OFF													
Cursor or 0 0 0 0 0 1 S R X X Move the cursor and shift the display without 40 µ S changing DDRAM contents. S/C=1: Display Shift; S/C=0:Cursor move. R/L=1:shift to right; R/L=0:shift to left.  Function 0 0 0 0 1 DNF X X Set interface data length (DL), number of display lines (N) and character font (F).DL=1: 8 bits; DL=0: 4 bits. N=1: 2 lines; N=0: 1 lines. F=1: 5X11 dots; F=0: 5X7 dots.  Set CG 0 0 0 1 ACG Set CG RAM address. CG RAM data is sent and received after this setting.  Set DD 0 0 1 ADD Set DD RAM address. DD RAM data is sent and received after this setting.  Read BF 0 1 B AC Read BUSY FLAG (BF) and the contents of the address counter. BF=1: internal operation; BF=0: can accept instruction.  Write Data 1 0 WRITE DATA Write data into DD RAM or CG RAM.  Read Data 1 0 READ DATA Read data from DD RAM or CG RAM.	control											. 5		
Display shift												B=0, Blink OFF.		
Display shift	Cursor or	0	0	0	0	0	1	S	R	Χ	Χ	Move the cursor and shift the display without	40 µ S	
Shift CL S/C=0:Cursor move. R/L=1:shift to right; R/L=0:shift to left.  Function O O O O D DNF X X Set interface data length (DL), number of display 40 µ S lines (N) and character font (F).DL=1: 8 bits; DL=0: 4 bits. N=1: 2 lines; N=0: 1 lines. F=1: 5X11 dots; F=0: 5X7 dots.  Set CG O O O D ACG Set CG RAM address. CG RAM data is sent and 40 µ S received after this setting.  Set DD O O D ACG Set DD RAM address. DD RAM data is sent and 40 µ S received after this setting.  Set DD O D D RAM address. DD RAM data is sent and 40 µ S received after this setting.  Read BF O D B AC Read BUSY FLAG (BF) and the contents of the ACC address counter. BF=1: internal operation; BF=0: can accept instruction.  Write Data 1 O WRITE DATA Write data into DD RAM or CG RAM.  S**  Read Data 1 O READ DATA Read data from DD RAM or CG RAM.								l	l					
Function Set	shift							С	L					
Set CG 0 0 0 1 ACG Set CG RAM address. CG RAM data is sent and 40 μ S received after this setting.  Set DD 0 0 1 ADD Set DD RAM address. DD RAM data is sent and 40 μ S received after this setting.  Read BF 0 1 B AC Read BUSY FLAG (BF) and the contents of the address counter. BF=1: internal operation; BF=0: can accept instruction.  Write Data 1 0 WRITE DATA Write data into DD RAM or CG RAM.  Read Data 1 0 READ DATA Read data from DD RAM or CG RAM.  40 μ S**												R/L=0:shift to left.		
Set CG 0 0 0 1 ACG Set CG RAM address. CG RAM data is sent and 40 μ S received after this setting.  Set DD 0 0 1 ADD Set DD RAM address. DD RAM data is sent and 40 μ S received after this setting.  Read BF 0 1 B AC Read BUSY FLAG (BF) and the contents of the address counter. BF=1: internal operation; BF=0: can accept instruction.  Write Data 1 0 WRITE DATA Write data into DD RAM or CG RAM.  Read Data 1 0 READ DATA Read data from DD RAM or CG RAM.  40 μ S**	Function	0	0	0	0	1	D	N	F	Χ	Χ	Set interface data length (DL), number of display	40 µ S	
Set CG 0 0 0 1 ACG Set CG RAM address. CG RAM data is sent and 40 \( \mu \) S received after this setting.  Set DD 0 0 1 ADD Set DD RAM address. DD RAM data is sent and 40 \( \mu \) S RAM Add seceived after this setting.  Read BF 0 1 B AC Read BUSY FLAG (BF) and the contents of the address counter. BF=1: internal operation; BF=0: can accept instruction.  Write Data 1 0 WRITE DATA Write data into DD RAM or CG RAM.  40 \( \mu \) Read Data 1 0 READ DATA Read data from DD RAM or CG RAM.	Set						L							
Set CG 0 0 0 1 ACG Set CG RAM address. CG RAM data is sent and 40 µ S received after this setting.  Set DD 0 0 1 ADD Set DD RAM address. DD RAM data is sent and 40 µ S received after this setting.  Read BF 0 1 B AC Read BUSY FLAG (BF) and the contents of the 0 µ S address counter. BF=1: internal operation; BF=0: can accept instruction.  Write Data 1 0 WRITE DATA Write data into DD RAM or CG RAM.  40 µ S**  Read Data 1 0 READ DATA Read data from DD RAM or CG RAM.												DL=0: 4 bits. N=1: 2 lines; N=0: 1 lines. F=1:		
RAM add received after this setting.  Set DD 0 0 1 ADD Set DD RAM address. DD RAM data is sent and 40 μ S received after this setting.  Read BF 0 1 B AC Read BUSY FLAG (BF) and the contents of the 0 μ S address counter. BF=1: internal operation; BF=0: can accept instruction.  Write Data 1 0 WRITE DATA Write data into DD RAM or CG RAM.  40 μ  Read Data 1 0 READ DATA Read data from DD RAM or CG RAM.														
Set DD 0 0 1 ADD Set DD RAM address. DD RAM data is sent and 40 µ S received after this setting.  Read BF 0 1 B AC Read BUSY FLAG (BF) and the contents of the 0 µ S address counter. BF=1: internal operation; BF=0: can accept instruction.  Write Data 1 0 WRITE DATA Write data into DD RAM or CG RAM.  40 µ S**  Read Data 1 0 READ DATA Read data from DD RAM or CG RAM.	Set CG	0	0	0	1			A(	CG	i	I	Set CG RAM address. CG RAM data is sent and	40 µ S	
RAM Add received after this setting.  Read BF 0 1 B AC Read BUSY FLAG (BF) and the contents of the 0 $\mu$ S address counter. BF=1: internal operation; BF=0: can accept instruction.  Write Data 1 0 WRITE DATA Write data into DD RAM or CG RAM. 40 $\mu$ Read Data 1 0 READ DATA Read data from DD RAM or CG RAM. 40 $\mu$	RAM add											received after this setting.		
RAM Add received after this setting.  Read BF 0 1 B AC Read BUSY FLAG (BF) and the contents of the 0 $\mu$ S address counter. BF=1: internal operation; BF=0: can accept instruction.  Write Data 1 0 WRITE DATA Write data into DD RAM or CG RAM. 40 $\mu$ Read Data 1 0 READ DATA Read data from DD RAM or CG RAM. 40 $\mu$	Set DD	0	0	1			Α	D	D			Set DD RAM address. DD RAM data is sent and	40 µ S	
& Addr F address counter. BF=1: internal operation; BF=0: can accept instruction.  Write Data 1 0 WRITE DATA Write data into DD RAM or CG RAM. 40 μ  to RAM Read Data 1 0 READ DATA Read data from DD RAM or CG RAM. 40 μ	RAM Add											received after this setting.		
can accept instruction.  Write Data 1 0 WRITE DATA Write data into DD RAM or CG RAM.  40 μ S**  Read Data 1 0 READ DATA Read data from DD RAM or CG RAM.  40 μ	Read BF	0	1	В			_	AC	;			Read BUSY FLAG (BF) and the contents of the	0 μ S	
can accept instruction.  Write Data 1 0 WRITE DATA Write data into DD RAM or CG RAM.  40 μ S**  Read Data 1 0 READ DATA Read data from DD RAM or CG RAM.  40 μ	& Addr			F								address counter. BF=1: internal operation; BF=0:		
Write Data 1 0 WRITE DATA Write data into DD RAM or CG RAM. 40 μ to RAM Read Data 1 0 READ DATA Read data from DD RAM or CG RAM. 40 μ												-		
to RAM S**  Read Data 1 0 READ DATA Read data from DD RAM or CG RAM. 40 µ	Write Data	1	0	١	ΝI	RI	TE	<u> </u>	DΑ	TA	1	•	40	μ
	to RAM												S**	
		1	0		RI	ΕA	νD	D	Α	ГΑ		Read data from DD RAM or CG RAM.	40	μ
	from RAM													

#### 10. Initialization By Instruction



# 11.Software Examples

# 8-BIT OPERATION 8 characters X 2 lines

Function	RS RW D7 D6 D5 D4 D3 D2 D1 D0	DISPLAY	DESCRIPTION
Power on delay			Initialization. No display appears.
Function set	0 0 0 0 1 1 0 0 X X		Sets 8-bit operation, 2-line display and 5*7
			dots character font.
Display OFF	0 0 0 0 0 0 1 0 0 0		Turn off display.
Display ON	0 0 0 0 0 0 1 1 1 0		Turn on display and cursor.
Entry Mode set	0 0 0 0 0 0 0 1 1 0		Set mode to increment the address by one
			and to shift the cursor to the right, at the
			time of write to the DD/CG RAM. Display
			is not shifted.
Write data to	1 0 0 1 0 0 1 1 1 1	0	Write "O". Cursor incremented by one and
CG/DD RAM			shift to right.
Write data to	1 0 0 1 0 1 0 0 1 0	OR	Write "R". Cursor incremented by one and
CG/DD RAM			shift to right
Write data to		ORIENT	Write "I" "E" "N" "T".
CG/DD RAM			
Set DDRAM	0 0 1 1 0 0 0 0 0 0	ORIENT	Set RAM address so that the cursor is
address			positioned at the head of the Second line
Write data to		ORIENT	Write "D" "S".
CG/DD RAM		DS_	
Cursor or display	0 0 0 0 0 1 0 0 X X	ORIENT	Shift only the cursor position to the left.
shift		DS	
Write data to		ORIENT	Write "I" "S" "P" "L" "A" "Y"
CG/DD RAM		DISPLAY	

### 4-bit operation (4-bits 1 line)

4-bit operation		<u> </u>	<b>Ο</b> ι τ.	<u> </u>		.0)	1	T
Function	RS	RW	D7	D6	D5	D4	Display	Description
power on delay								Initialization. No display appears.
Frnction set	0	0	0	0	1	0		Sets to 4-bit operation. In this case, operation is handled as 8-bits by initialization,a nd Only this instruction completes with one write.
Frnction set	0	0	0	0	1 X	0 X		Sets 4 -bit operation, 1-line display and 5*7 dot character font. (number of display lines and character fontscannot be changed hence after.)
Display ON/OFF Control	0		0 1	0	0	-	_	Turn on display and cursor.
Entry Mode Set	0	0	0	0	0		_	Turn on display and cursor.
Write data to CG/DD/ARM	1 1	-	0 1	1 1	0			Write "O". Curaor incrementer by one and shift to right.
						•	same as 8-bi	t operation

### 12.Quality units

### 12.1 Purpose

This standard for quality assurance should define the quality of LCD module products to customer by EASTERNTIONIC LCD GROUP.

### 12.2 Scope

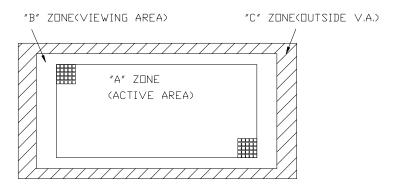
This document defines general provisions as well as inspection standards for LCD module supplied by EASTERNTIONIC LCD GROUP, except for those with special requirements from customer.

#### 12.3 Definition

#### 12.3.1 Definition of area

A Zone: Active area. B Zone: Viewing area

C Zone: Outside viewing area.



#### 12.3.2 Definition of size

Large size(L): 1~6 pcs LCD screens are cut out of from each 14"×16" mother glass. Middle size(M):  $7 \sim 50$  pcs LCD screens are cut out of from each  $14" \times 16"$ Small size(S): more than 50 pcs LCD screens are cut out of from each 14"×16" glass.

### 12.4 Quality Specification

### 12.4.1 Conditions of Cosmetic Inspection

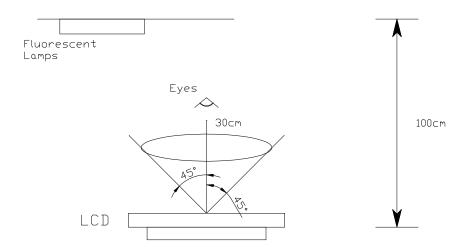
### 12.4.1 Test should be conducted under the following conditions:

Ambient temperature :22 $\pm$ 5°C. Ambient humidity:  $65 \pm 20\%$ RH

Ambient Luminance: 40-watt fluorescent lamp.

An appearance test should be conducted by human sight at approximately 30 cm distance

from the LCD module under fluorescent light. Distance between LCD and fluorescent lamps should be 100 cm or more. Viewing direction for inspection is  $45^{\circ}$  from vertical against LCD.



#### 12.4.1.2 When test the model of transmissive product must add the reflective plate.

### 12.4.2 Sampling plan

Unless otherwise agreed in writing, the sampling inspection shall be applied to the incoming inspection of customer.

- Lot size: Quantity of shipment lot per model
- Sampling type: Normal inspection, single sampling
- Sampling Level: Level II
- Sampling table: GB/T2828.1.1(GB-national standard of China)

#### 12.4.3 Classification of defects and Acceptable quality level

Defects and classified as either a major or minor defect defined as bellows:

- Major defect: It is a defect that is likely to result in failure or to reduce materially the usability of the product for the intended function.
- Minor defect: It is a defect that will not result in functioning problem with deviation calssifiec.

The AQL for major and minor defects is defined as follows:

Partition	Definition	AQL
Major defect	Functional defective as product	0.4
Minor defect	Satisfy all functions as product but not satisfy cosmetic standard	1.0

#### 12.4.4 Applicable instrument

- LCD module tester
- Multimeter
- Caliper
- Defect size filming standard

# 12.4.5 Inspection quality criterion

# 12.4.5.1 LCD panel part

The inspection specification as following list:

		Description of defects	Inspection criterion		S	Drawing pecification
Major defect	1.Non-display	Product no function	No	ot accept		
	2.LCD with wrong view direction`	Difference in Spec.	No	ot accept		
	3.Segment missing	Part or all pattern do not light up	No	ot accept		
	4.Occur high current	Current exceed designed value	No	ot accept		
	5. LC leakage	LC does not fulfill the glass cell	No	ot accept		
	6.Deviation from drawing	LCM Dimension difference from drawing and over tolerance	•	dimensions noted specification		
	7.Wrong type applied	Wrong polarizer attachment	No	ot accept		
		Pin attached wrong type applied	Not accept			
	8.Incorrect pins quality	Pin attached wrong quantity applied	Not accept			
Minor defect	9.Pattern deformation	Segment fatter or smaller	Dimension (mm) A≤0.1	Acceptable no  Not count (Should not be connito next dot)		A

			0.10 <a≤0.15< th=""><th>1 pc / dot(dosegment) or less 2 pcs / cell or less (Should not be connect to next dot)</th><th></th></a≤0.15<>	1 pc / dot(dosegment) or less 2 pcs / cell or less (Should not be connect to next dot)	
			B ≤ 0.10	Not count	
Minor defect	10.Pinholes	Black spot/white spot at activated state	distance an under  2. Middle si Diameter(mn $\Phi \le 0.1$ $0.15 < \Phi \le 0.25$ $0.25 < \Phi \le 0.35$ $\Phi > 0.35$ 3. Small siz Diameter(mn $\Phi \le 0.1$ $0.15 < \Phi \le 0.25$ $0.25 < \Phi \le 0.30$ $\Phi > 0.30$ 4. For the contraction of equal lattice's 5. Only allow segment 6. The near between 20mm  Remarks: Regative type of FSTN), with now white dot size $0.2 \text{mm}(\Phi \le 0.1)$ is lower 0.1 is lower 0.2 voltage, it voltage, it can	an't be found at 1m and will not enlarge electronic test ze LCD a) Accept QTY 5 Not count 3 1 0 e LCD a) Accept QTY 5 Not count 2 1 0 lot pattern: accept if of defect is less than 1 to half of one est diatance allowed	$\Phi = (X+Y)/2$

11.Blemishes	Black spot/dust	Positive panel:	•
and foreign	on	1.A zone	
matters	LCD(non-display	- Large size LCD	<b>▶</b> ★ '
	)	Accept if can't find at 1m	
		distance and will not enlarge	
		under electronic test:	$\Phi = (X+Y)/2$
		-Middle size LCD	
		Diameter(mm) Accept QTY	
		$\Phi \le 0.15$ Not count	
		$0.15 < \Phi \le 0.25$ 3	
		0.25<Φ≤ 0.35 1	
		$\Phi > 0.35$ 0	
		-Small size LCD	
		Diameter(mm) Accept QTY	
		$\Phi \le 0.15$ Not count	
		$0.15 < \Phi \le 0.25$ 2	
		$0.25 < \Phi \le 0.30$ 1	
		$\Phi > 0.30$ 0	
		2.B zone	
		1.5 times of acceptable largest	
		diameter size of Zone A	
		3.C zone	
		Notcount.	
		Negative panel:	
		1. A zone	
		-Large size LCD	
		Diameter(mm) Accept QTY	
		$\Phi$ ≤ 0.15 Not count	
		0.15<Ф≤0.30 4	
		$0.30 < \Phi \le 0.50$ 1	
		$\Phi > 0.50$ 0	
		-Middle&small size LCD	
		Diameter(mm) Accept QTY	
		$\Phi \le 0.15$ Not count	
		0.15<Ф≤0.25 3	
		$\Phi > 0.25$ 0	
		2. B zone	
		1.5 times of acceptable largest	
		diameter size of Zone A	
		3.C zone	
		No count	
		The nearest diatance allowed	
		between two black spot is 20mm	
		T	

12.Black	Scratch on glass	Positive panel:	
lines and	or polarizer	1.A zone	. L .
scratches	surface.And	- Large size LCD	
	foreign linear	Accept if can't find at 1m	
	matters in LCD	distance and will not enlarge	
		under electronic test.	
		-Middle size LCD	
		Diameter(mm) Accept QTY	
		W≤ 0.02 Not count	
		$0.02 < W \le 0.03, L \le 4$ 2	
		$0.03 < W \le 0.05, L \le 3$ 2	
		$0.02 < W \le 0.03, L > 4 $ 0	
		$0.03 < W \le 0.05, L > 3 $ 0	
		W>0.05 As the spot criteria.	
		-Small size LCD	
		Diameter(mm) Accept QTY	
		W≤ 0.02 Not count	
		$0.02 < W \le 0.03, L \le 4$ 2	
		$0.03 < W \le 0.05, L \le 2$	
		0.02< W≤ 0.03,L >4 0	
		$0.03 < W \le 0.05, L > 2 $ 0	
		W>0.05 As the spot criteria.	
		2.B zone	
		1.5 times of acceptable largest	
		diameter size of Zone A	
		3.C zone	
		Notcount.	
		Negative panel:	
		1. A zone	
		-Large size LCD	
		Diameter(mm) Accept QTY	
		W≤ 0.02 Not count	
		$0.02 < W \le 0.03, L \le 5$ 3	
		$0.03 < W \le 0.05, L \le 4 \qquad 2$	
		$0.02 < W \le 0.03, L > 5 0$	
		$0.03 < W \le 0.05, L > 4 $ 0	
		W>0.05 As the spot criteria.	
		-Middle size LCD	

			Diameter(mm) Accept QTY $W \le 0.02$ Not count $0.02 < W \le 0.03$ , $L \le 4$ 2 $0.03 < W \le 0.05$ , $L \le 2$ 2 $0.02 < W \le 0.03$ , $L > 3$ 0 $0.03 < W \le 0.05$ , $L > 2$ 0 $W > 0.05$ As the spot criteriaSmall size LCD Diameter(mm) Accept QTY $W \le 0.02$ Not count $0.02 < W \le 0.03$ , $L \le 3$ 2 $0.03 < W \le 0.05$ , $L \le 3$ 1 $0.02 < W \le 0.03$ , $L \ge 3$ 0 $0.03 < W \le 0.05$ , $L \ge 3$ 1 $0.02 < W \le 0.03$ , $L \ge 3$ 0 $0.03 < W \le 0.05$ , $L \ge 2$ 0 $0.03 < U \le 0.05$ , $U \ge 0.05$ , $U \ge 0.05$ As the spot criteria.	
Mintor defect	13. Scratch on PI coating	PI coating scratched	The visible scratch of A zone can not be accepted at 30cm view distance.	
Mintor defect	14. Rainbow	Arches, circular or parallel colorful spread	According to the limit specimen	
Mintor defect	15. Bubbles or wrinkles in polarizer	Bubbles or wrinkles between polarizer and glass	A zone:The visible defect can not be accepted at 30cm view distance.  B zone: Not count	
Mintor defect	16. Position of polarzer attachment	Wrong polarizer attachment in position or dimension	Polarizer protruding from edge of glass and exceeding/within the maximum external dimension of LCD	

Mintor	17. Ink	17.1 Ink	Not acce	pt			
defect	printing	line/pattern					
	defect	broken					
		17.2 Ink pattern/line	_	f the thick n equal to		-	
		jagged		r accordii			
		J.,88	specimen		6		
		17.3 Light			with	current	
		leakage		ht appears			
			_	le or scra misalignr			
				nhole spec		_	
		17.4 Ink printing	Reject if than 1/2	the thick	or thin	in more	
		pattern/line uneven		w. hen W1-V	V2<1/3V	V	
							W1   W2
Mintor	18. Pin defect	18.1 Corrosion	Pin	incomin	~	defect:	
defect	18. Fill defect	or foreign		incomin damage(i	_		
		material on		damaged)			
		terminal legs		om glass	s or t	erminal	
		10 A D'	legs.Not		· C·	··	
		18.2 Pin deviation over	Accordin	ng to the s	pecifica	шоп	
		tolerance					
Mintor	19. Chipped	19.1 Chip in	a	b	c	accept	
defect	glass on	lead contact				QTY	
	comer	area.	a≤5mm L>5m	b≤W	c≤T	3	
			m			3	ITO
			a <l< td=""><td>b≤W</td><td>c≤T</td><td>3</td><td></td></l<>	b≤W	c≤T	3	
							T
			L<5m				b o o
			m				
		19.2 Others	Not exc	ceed 1/2			AT.
			width of	seal	c≤T	3	
							100

			T	Т	1	1	Т
Mintor	20. Glass	chip on edge	a	b	c	accept	b * 0
defect						QTY	
			a≤5mm	Not	c≤T	3	
				exceed			
				1/2			Ţ
				width			
				of seal			
	21. Clipped	21.1Glass chip	a	b	c	accept	ITD
Mintor	electrode pad	on ITO edge				QTY	
defect			a≤4mm	b≤W/4	c≤T	3	
			(and				
			not				<b>→</b> ~ ~
			exceed				6 1
			4 ITO				
			termina				
			1				
		21.2 Glass chip	a	b	c	accept	b
		on ITO back				QTY	
			a≤5mm	b≤W/3	c≤T	3	
							l W
Mintor	22.	Extended crack	b		accept	QTY	
defect	Mechanical	inspector shall					9 W
	damage	attempt to	b≤W/4		2		
		remove the chip					
		with					
		tweezers,re-eval					b /
		uate if the					→ <b>←</b> ○
		remaining defect					
		is still a crack or					\_/
	_	a chip					<u>→</u>
Mintor	23.Gla	Not acce	pt				
defect							
<del></del>							1

#### Remark:

The minimum space between any 2 defects(spot,dirt) should more than 20mm, and max. allowed defect QTY in total:

Large size LCD: Zone A≤ 5/unit, Zone B≤ 5/unit; Middle size LCD: Zone  $A \le 3/unit$ , Zone  $B \le 3/unit$ ; Small size LCD: Zone A≤ 2/unit, Zone B≤ 2/unit;

# 12.4.5.2 Other part

The inspection specification as following list:

NO.	Items	Criterion of defects	AQL
1	Backlight	<ol> <li>Lumination source flickers.</li> <li>Using spot, lines and contamination standard of LCD to judge the spots or scratches defect on backlight.</li> </ol>	Major Minor
		3. Not allow unlighted on backlight.	Major
		4. Colour and luminance of backlight should correspond its specification.	Major
2	PCB,COB	1.COB seal may not have pinholes larger than 0.2mm or contamination.	Minor
		2.COB seal surface may not have pinholes through to the IC.	Minor
		3. The height of COB should not exceed the height indicated in the assembly diagram.	Major
		4. Beyond 2mm of the seal area, there may not have sealant on the PCB.	Minor
		5.No oxidation or contamination on PCB connector.	Minor
		6.Parts on PCB should correspond the characteristic, and not allow wrong parts, missing parts or additional parts.	Major
		7. The jumper on the PCB should correspond to the characteristic.	Minor
		8. The solder which gets on bezel, LED pad, zebra pad or screw hole pad should be smoothed down.	Major
		No unmelted solder pastes on the PCB.	Minor
3	Soldering	2. No cold solder joints, solder connection missing, oxidation of solder.	Minor
		3. No short circuits in components on PCB.	Minor
4	General Appearance	1. No oxidation, contamination, curves, cracks or bends on interface Pin of TCP.	Minor
		2. No solder residue or solder balls on product.	Minor
		3. The IC on TCP may not be damaged.	Major
		4. The residual rosin or tin oil of soldering(component or chip component) is not turned into brown or black colour.	Minor
		5. Packing method correspond the specification.	Major
		6. Dimension and structure correspond the specification sheet.	Major
		7. No dirt and break on the heat seal.	Major

# 12.5 Reliability

The LCD module shall not fail the following reliability test.

Item	Condition	Criterion			
High temperature	$70^{\circ}\text{C} \pm 2^{\circ}\text{C}$ , 8 hou				
operation					
Low temperature	$-20^{\circ}\text{C} \pm 2^{\circ}\text{C}$ , 8 ho	urs	1.Total current		
operation			consumption		
Humidity	Operation	$40^{\circ}\text{C} \pm 2^{\circ}\text{C},93\% \pm 2\%\text{RH,8}$	should be below		
		hours	double of initial		
	Storage	$40 ^{\circ}\text{C} \pm 2 ^{\circ}\text{C},93\% \pm 2\% \text{RH},$	value.		
		24 hours	2.Cosmetic defects		
High temperature	+80°C ±2°C, 10 h	nours	should not be		
storage			happened		
Low temperature	-30°C ±2°C, 10 h	ours			
storage					
Thermal shock	-20°C +70°C				
storage	60min~60min, 5 cy				
Vibration test	Amplitude:0.7~1.0	mm,frequency:50Hz,30min			
	in each direction(X	(X,Y,Z)			
Shock test	To be measured aft	er dropping from 60cm or			
	80cm high on the c	oncrete surface in packing			
	state.(weight≥15K	Kg,dropping height 60cm;			
	Weight < 15 Kg, dro	pping height 80cm)			
		Duomino method			
		Dropping method corner dropping			
	<u> </u>	D A corner: once			
	G	Edge dropping			
	D	A B,C,D edge: once Face dropping			
	60/8	80cm Face dropping E,F,G face: once			
		Concrete Surface			
	///////////////////////////////////////				

Remark: The function test shall be conducted after 4 hours storage at the normal temperature and humidity after removed from the test chamber.

### 13. Precaution For Using LCM

#### 1. LIQUID CRYSTAL DISPLAY (LCD)

LCD is made up of glass, organic sealant, organic fluid, and polymer based polarizers. The precautions should be taken when handing,

- (1). Keep the temperature within range of use and storage. Excessive temperature and humidity could cause polarization degredation, polarizer peel off or bubble.
- (2). Do not contact the exposed polarizers with anything harder than an HB pencil lead. To clean dust off the display surface. Wipe gently with cotton. Chamois or other soft material soaked in petroleum benzin.
- Wipe off saliva or water drops immediately. Contact with water over a long period of time may cause polarizer deformation or color fading, while an active LCD with water condensation on its surface will cause corrosion of ITO electrodes.
- (4). Glass can be easily chipped or cracked from rough handing. especially at corners and edges.
- (5). Do not drive LCD with DC voltage.

#### 2. Liquid Crystal Display Modules

#### 2.1 Mechanical Considerations

LCM are assembled and adjusted with a high degree of precision. Avoid excessive shocks and do not make any alterations or modifications. The following should be noted.

- (1). Do not tamper in any way with the tabs on the tabs on the metal frame.
- (2). Do not modify the PCB by drilling extra holes, changing its outline, moving its components or modifying its pattem.
- (3). Do not touch the elastomer connector, especially insert an backlight panel (for example, EL).
- (4). When mounting a LCM make sure that the PCB is not under any tress such as bending or twisting. Elastomer contacts are very delicate and missing pixels could result from slight dislocation of any of the elements.
- (5). Avoid pressing on the metal bezel, otherwise the elastomer connector could be deformed and lose contact, resulting in missing piels.

#### 2.2. Static Electricity

LCM contains CMOS LSI's and the same precaution for such devices should apply, namely

(1). The operator should be grounded whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.

- (2). The modules should be kept in antistatic bags or other containers resistant to static for storage.
- (3). Only properly grounded soldering irons should be used.
- (4). If an electric screwdriver is used, it should be well grounded and shielded from commutator sparks.
- (5). The normal static prevention measures should be observed for work clothes and working benches; for the latter conductive (rubber) mat is recommended.
- (6). Since dry air is inductive to statics, a relative humidity of 50-60% is recommended.
- 2.3. Soldering
- (1). Solder only to the I/O terminals.
- (2). Use only soldering irons with proper grounding and no leakage.
- (3). Soldering temperature: 280  $^{\circ}\text{C} \pm 10^{\circ}\text{C}$
- (4). Soldering time: 3 to 4 sec.
- (5). Use eutectic solder with resin flux fill.
- (6). If flux is used, the LCD surface should be covered to avoid flux spatters. Flux residue should be removed after wards.
- 2.4. Operation
- (1). The viewing angle can be adjusted by varying the LCD driving voltage V0.
- (2). Driving voltage should be kept within specified range; excess voltage shortens display life.
- Response time increases with decrease in temperature.
- Display may turn black or dark blue at temperatures above its operational range; this is (however not pressing on the viewing area) may cause the segments to appear "fractured".
- (5). Mechanical disturbance during operation (such as pressing on the viewing area) nay cause the segments to appear "fractured".

#### 2.5. Storage

If any fluid leaks out of a damaged glass cell, wash off any human part that comes into contact with soap and water. Never swallow the fluid. The toxicity is extremely low but caution should be exercised at all the time.

#### 2.6. Limited Warranty

Unless otherwise agreed between EASTERNTRONIC and customer, EASTERNTRONIC will replace or repair any of its LCD and LC, which is found to be defective electrically and visually when inspected in accordance with EASTERNTRONIC acceptance standards, for a period on one year fron data of shipment. Confirmation of such date shall be based on freight documents. The warranty liability of EASTERNTRONIC is limited to repair and/or replacement on the terms set forth above. EASTERNTRONIC will not responsible for any subsequent or consequential events.

## 14. Declaration of conformity regarding the limitation of dangerous substances

## 深圳易事通液晶显示模块有限公司

#### SHENZHEN EASTERNTRONIC LCM CO., LTD.

4F, B3 Building, FuYuan Industrial Zone, FuYong Town,

### BaoAn District, ShenZhen, P.R.China

## DECLARATION OF CONFORMITY REGARDING THE LIMITATION OF DANGEROUS SUBSTANCES

WE, SHENZHEN EASTERNTRONIC LCM CO., LTD,

Declare that the product of CS4002B-D-BSXTSWN-100 complies with: The directive 2002/95/EC Dated 2003/01/27 regarding the limitation of dangerous substances, in particular to clause 4 which forbids the use of the following elements:

- Lead
- Mercury
- Cadmium
- Hexavalant chromium
- Polybrominated biphenyls
- Polybrominated diphenylethers

And to the annex which points out the exempted implementations  $\square$  To the directive 73/23/eec dated 1973/02/19 and the standard EN60335-1 regarding prohibition of following elements:

- 0ils containing polychlorinated biphenyl
- Asbestos
- Radioactive substances

Name: Ding

SHENZHEN EASTERNTRONIC LCM CO., LTD.

Issued on Feb 20, 2009

According with the proposal of Technical Adaption Committee (TAC) of a limit of 0.1% by weight for lead hexavalent chromium, mercury, PBBs and PBDRs and 0.01% by weight for Cadmium.